

WHAT IS CLAIMED IS:

1. A preparation method for inductance element, comprising the following steps:
prepare a substrate;
prepare at least one coil on said substrate; said at least one coil having an external side;
5 prepare a conductive material to connect the external side of said at least one coil to
function as an plating electrode; and
form a multileveled multiple-layered magnetic structure on said at least one coil.
wherein material for said multiple-layered magnetic structure comprises a soft
magnetic material; and
10 wherein said multileveled magnetic structure is prepared through intermittent plating.
2. The method according to claim 1 wherein said at least one coil is a winded
enameled wire coil, a planar coil or a coil formed on a printed circuit board
3. The method according to claim 1, wherein said conductive material is metalized
such that said multiple-layered magnetic structure may be developed on said at least one coil.
- 15 4. The method according to claim 1 wherein said soft magnetic material comprises a
21% Permalloy alloy or a super Permalloy.
5. An inductance element prepared according to anyone of claims 1-4.